

## PMP10834 REV A Bill of Materials

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
IPC81	1		PMP10834	Any	Printed Circuit Board	
C1	1	100pF	C1608C0G1H101J	TDK	CAP, CERM, 100pF, 50V, +/-5%, C0G/NP0, 0603	0603
C2	1	100uF	EEU-EB1E101S	Panasonic	CAP, AL, 100uF, 25V, +/-20%, TH	6.3x11.2mm
C3	1	1uF	12063C105KAT2A	AVX	CAP, CERM, 1uF, 25V, +/-10%, X7R, 1206	1206
C4	1	1uF	0805YD105KAT2A	AVX	CAP, CERM, 1uF, 16V, +/-10%, X5R, 0805	0805
C5	1	100pF	06033C101KAT2A	AVX	CAP, CERM, 100pF, 25V, +/-10%, X7R, 0603	0603
C6	1	2200pF	06031C222JAT2A	AVX	CAP, CERM, 2200 pF, 100 V, +/- 5%, X7R, 0603	0603
C7	1	0.01uF	06031C103KAT2A	AVX	CAP, CERM, 0.01 uF, 100 V, +/- 10%, X7R, 0603	0603
C8	1	0.022uF	C0603C223K4RACTU	Kemet	CAP, CERM, 0.022 uF, 16 V, +/- 10%, X7R, 0603	0603
C9	1	1uF	C3216X7R1H105K	TDK	CAP, CERM, 1uF, 50V, +/-10%, X7R, 1206	1206
C10, C11	2	6.8uF	400AX6R8M8x11	Rubycon	CAP, AL, 6.8uF, 400V, +/-20%, TH	8x11
C12, C13, C101, C102	4	100uF	GRM31CR60J107ME39L	MuRata	CAP, CERM, 100 uF, 6.3 V, +/- 20%, X5R, 1206	1206
C14	1	0.1uF	06033C104JAT2A	AVX	CAP, CERM, 0.1 uF, 25 V, +/- 5%, X7R, 0603	0603
C103	1	470uF	6SEPC470MW	Panasonic	CAP, AL, 470 uF, 6.3 V, +/- 20%, 0.007 ohm, TH	6.3x9mm
C104	1	3900pF	GRM188R71H392KA01D	MuRata	CAP, CERM, 3900 pF, 50 V, +/- 10%, X7R, 0603	0603
D1	1	0.63V	BAV99WT1G	Fairchild Semiconductor	Diode, P-N, 70V, 0.2A, SOT-323	SOT-323
D2	1	100V	MMDL914-TP	Micro Commercial Component	Diode, Switching, 100V, 0.2A, SOD-323	SOD-323
D3	1	600V	ES1J-TP	Diodes Inc.	DIODE FAST REC 600V 1A DO214AC	SMA
D4	1	1000V	1N4007	Fairchild Semiconductor	Diode, P-N, 1000 V, 1 A, TH	DO-41
D5	1	600V	MURS360T3G	ON Semiconductor	Diode, Ultrafast, 600 V, 3 A, SMC	SMC
F1	1		RST 500	Bel Fuse	Fuse, 0.5A, 250V, TH	8.35x7.7x4mm
L1	1	47uH	MSD1583-473MEB	Coilcraft	Coupled inductor, 47 uH, 5.4 A, 0.1 ohm, +/- 20%, SMD	IND_14.8x8.6x14.8mm, SMD
L2	1	1mH	7447462102	Würth Elektronik eiSos	Inductor, Unshielded Drum Core, Ferrite, 1 mH, 0.25 A, 4.38 ohm, TH	D6 x 8.5mm
Line	1	Red	5000	Keystone	Test Point, Miniature, Red, TH	Red Miniature Testpoint
Neutral, TP3	2	Black	5001	Keystone	Test Point, Miniature, Black, TH	Black Miniature Testpoint
Q1	1	500V	FQB5N50CTM	Fairchild Semiconductor	MOSFET, N-CH, 500 V, 5 A, DDPK	DDPAK
R1	1	511	CRCW0805511RFKEA	Vishay-Dale	RES, 511, 1%, 0.125 W, 0805	0805
R2	1	7.87k	CRCW06037K87FKEA	Vishay-Dale	RES, 7.87 k, 1%, 0.1 W, 0603	0603
R3, R9	2	2.00k	CPF0603B2K0E	TE Connectivity	RES, 2.00 k, 0.1%, 0.063 W, 0603	0603
R4	1	15	CRCW060315R0JNEA	Vishay-Dale	RES, 15 ohm, 5%, 0.1 W, 0603	0603
R5, R6	2	10.0k	ERJ-3EKF1002V	Panasonic	RES, 10.0 k, 1%, 0.1 W, 0603	0603
R7	1	511	CRCW0603511RFKEA	Vishay-Dale	RES, 511 ohm, 1%, 0.1W, 0603	0603
R8, R13	2	2.49k	CRCW06032K49FKEA	Vishay-Dale	RES, 2.49k ohm, 1%, 0.1W, 0603	0603
R10	1	10.0k	CRCW060310K0FKEA	Vishay-Dale	RES, 10.0k ohm, 1%, 0.1W, 0603	0603
R11	1	100k	CRCW0603100KFKEA	Vishay-Dale	RES, 100 k, 1%, 0.1 W, 0603	0603
R12, R14	2	330k	CRCW2512330KJNEG	Vishay-Dale	RES, 330 k, 5%, 1 W, 2512	2512
R15	1	10.0	CRCW120610R0FKEA	Vishay-Dale	RES, 10.0 ohm, 1%, 0.25W, 1206	1206
R16	1	100k	CRCW0603100KFKEA	Vishay-Dale	RES, 100k ohm, 1%, 0.1W, 0603	0603
R17	1	0.33	v	Yageo	RES 0.33 OHM 1W 1% 2010 SMD	2010
R18, R19	2	1.0k	CRCW12061K00JNEA	Vishay-Dale	RES, 1.0 k, 5%, 0.25 W, 1206	1206
TP1	1	Yellow	5004	Keystone	Test Point, Miniature, Yellow, TH	Yellow Miniature Testpoint
TP2	1	White	5002	Keystone	Test Point, Miniature, White, TH	White Miniature Testpoint
U1	1		PC817X4NSZ0F		Opto-Isolator, 1 Channel, TH	DIP-4

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U2	1		UCC28C45D	Texas Instruments	BiCMOS LOW-POWER CURRENT-MODE PWM CONTROLLER, D0008A	D0008A
U3	1		TL431AIDBZR	Texas Instruments	Adjustable Precision Shunt Regulator, 34 ppm / degC, 100 mA, -40 to 85 degC, 3-pin SOT-23 (DBZ), Green (RoHS & no Sb/Br)	DBZ0003A
J1	0	2x1	1715721	Phoenix Contact	Conn Term Block, 2POS, 5.08mm, TH	2POS Terminal Block

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